

## Description

The AP30V02DF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

## General Features

$V_{DS} = -20V$   $I_D = -30A$

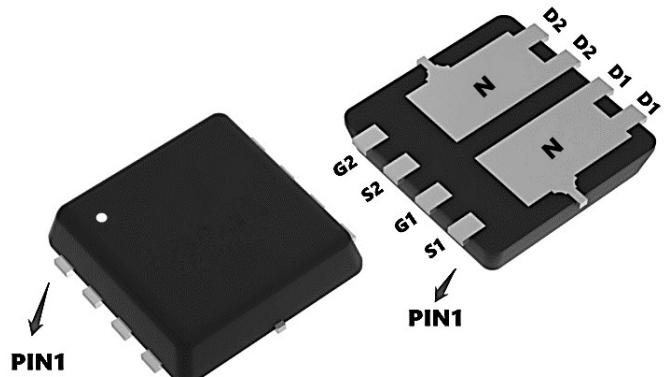
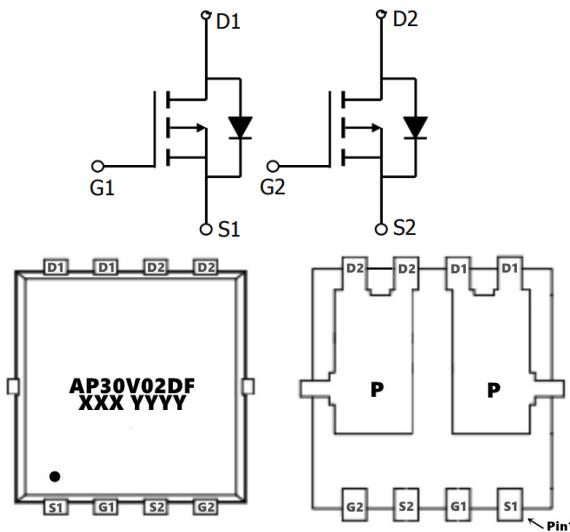
$R_{DS(ON)} < 16m\Omega$  @  $V_{GS}=4.5V$  (**Type: 12.5m $\Omega$** )

## Application

Lithium battery protection

Wireless impact

Mobile phone fast charging



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP30V02DF	PDFN3*3-8L	AP30V02DF XXX YYYY	5000

## Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

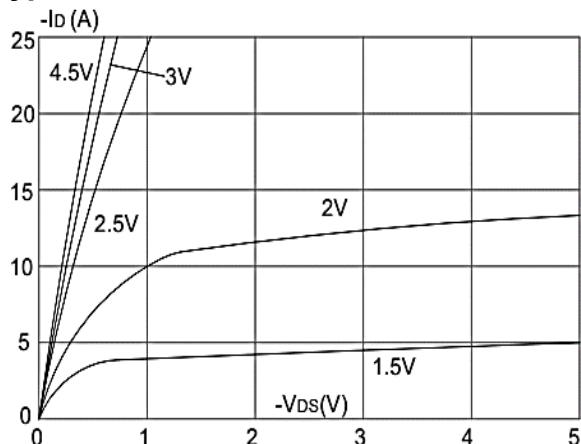
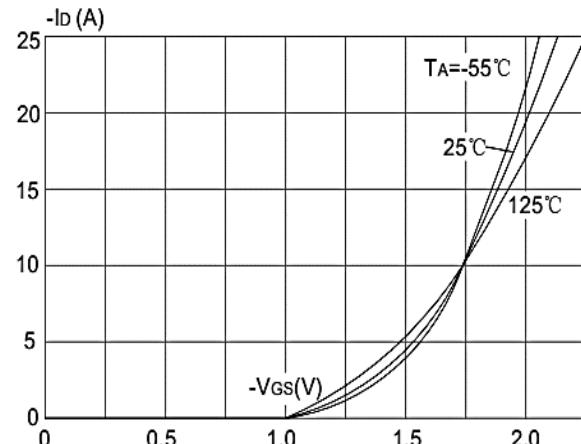
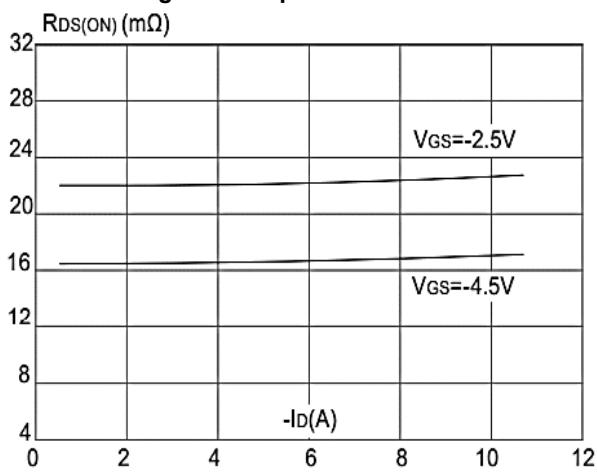
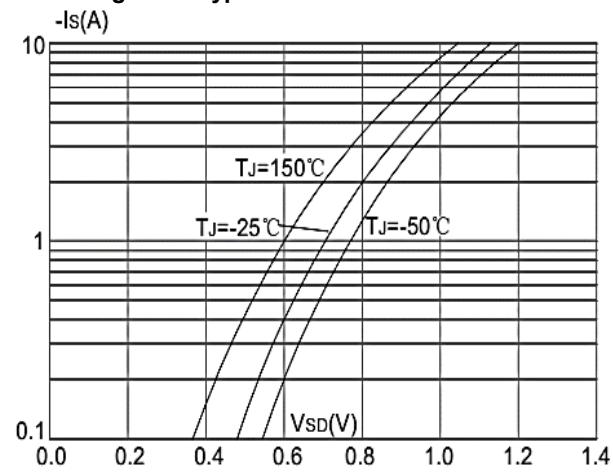
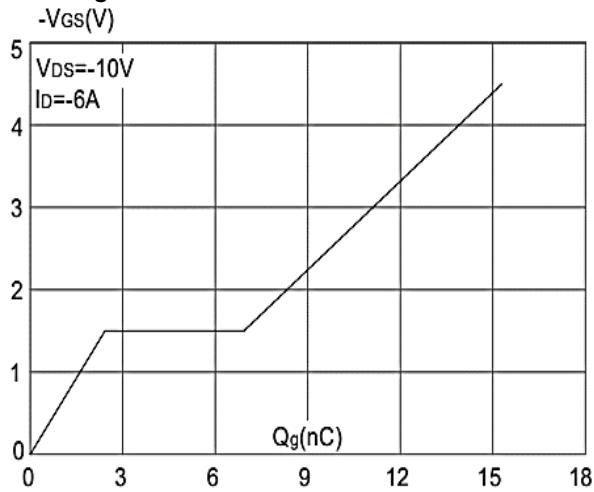
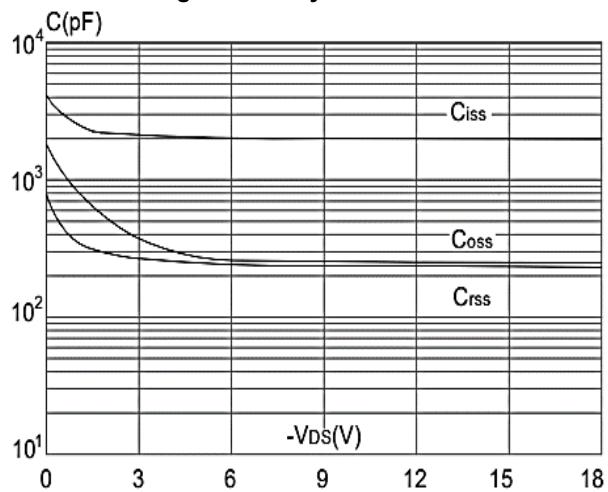
Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-30	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-19	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-90	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	1.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	12	°C/W

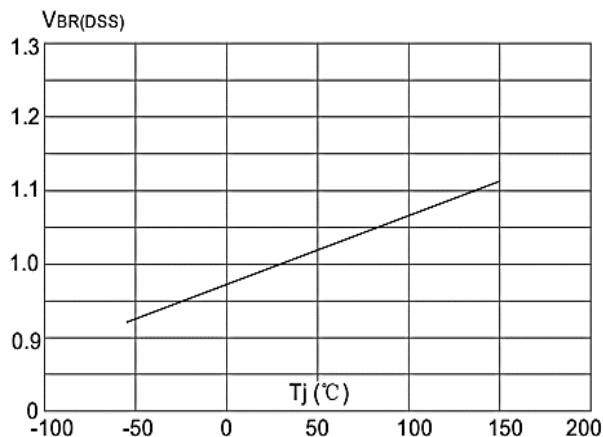
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-20	-23	---	V
$\Delta BVDSS/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.012	---	$\text{V}/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-4.5\text{V}$ , $I_D=-20\text{A}$	---	12.5	16	$\text{m}\Omega$
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-2.5\text{V}$ , $I_D=-10\text{A}$	---	16.5	28	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=-250\mu\text{A}$	-0.5	0.6	-1.2	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	2.94	---	$\text{mV}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=-20\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 12\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
Q <sub>g</sub>	Total Gate Charge (-4.5V)	$V_{DS}=-10\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D=-6\text{A}$	---	15.3	---	nC
Qgs	Gate-Source Charge		---	2.2	---	
Qgd	Gate-Drain Charge		---	4.4	---	
Td(on)	Turn-On Delay Time	$V_{DD}=-10\text{V}$ , $V_{GS}=-4.5\text{V}$ , $R_G=3.3\Omega$ , $I_D=-10\text{A}$	---	10	---	ns
T <sub>r</sub>	Rise Time		---	31	---	
Td(off)	Turn-Off Delay Time		---	28	---	
T <sub>f</sub>	Fall Time		---	8	---	
C <sub>iss</sub>	Input Capacitance	$V_{DS}=-10\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	2000	---	pF
C <sub>oss</sub>	Output Capacitance		---	242	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	231	---	
I <sub>S</sub>	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-20	A
ISM	Pulsed Source Current <sup>2,4</sup>		---	---	-48	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_S=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V

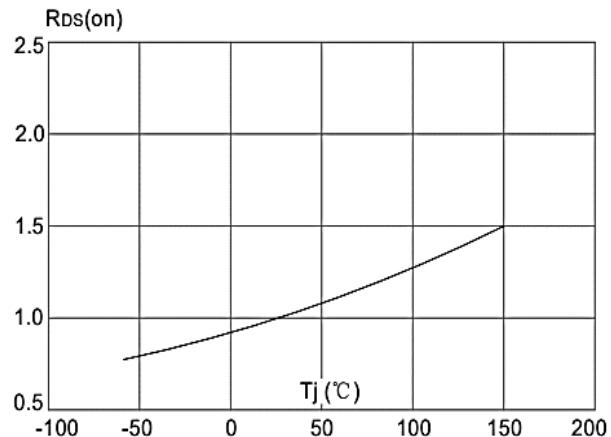
**Note :**

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
- 3、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4、The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

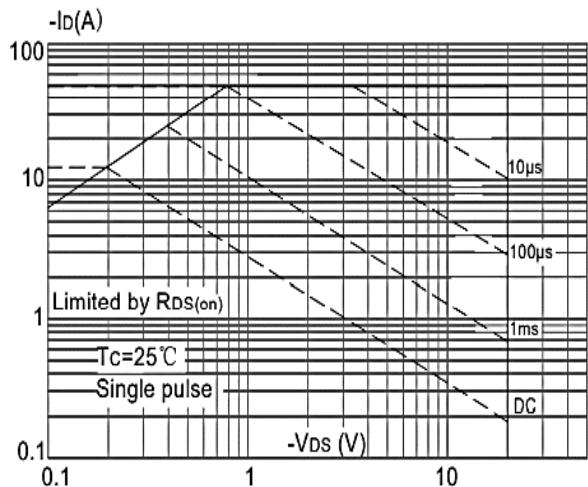
**Typical Characteristics**

**Figure 1: Output Characteristics**

**Figure 2: Typical Transfer Characteristics**

**Figure 3: On-resistance vs. Drain Current**

**Figure 4: Body Diode Characteristics**

**Figure 5: Gate Charge Characteristics**

**Figure 6: Capacitance Characteristics**



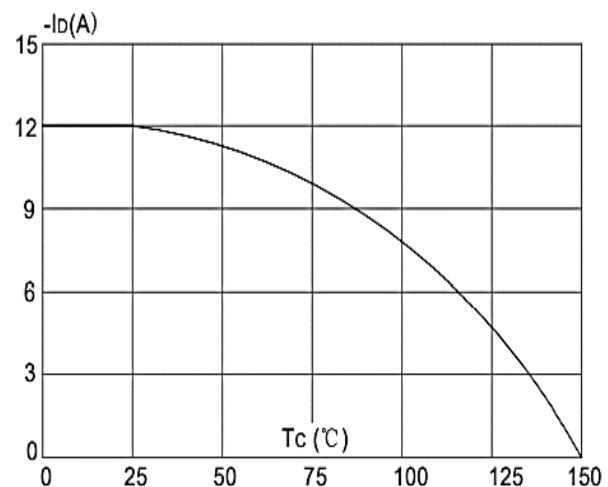
**Figure 7: Normalized Breakdown Voltage vs Junction Temperature**



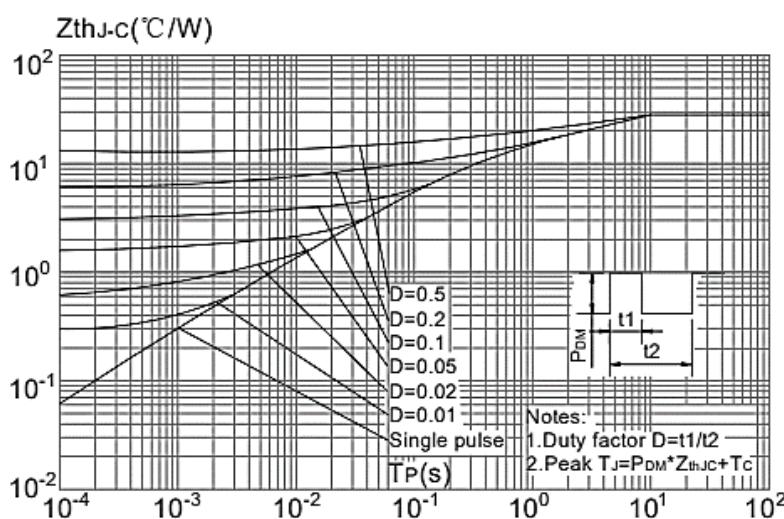
**Figure 8: Normalized on Resistance vs. Junction Temperature**



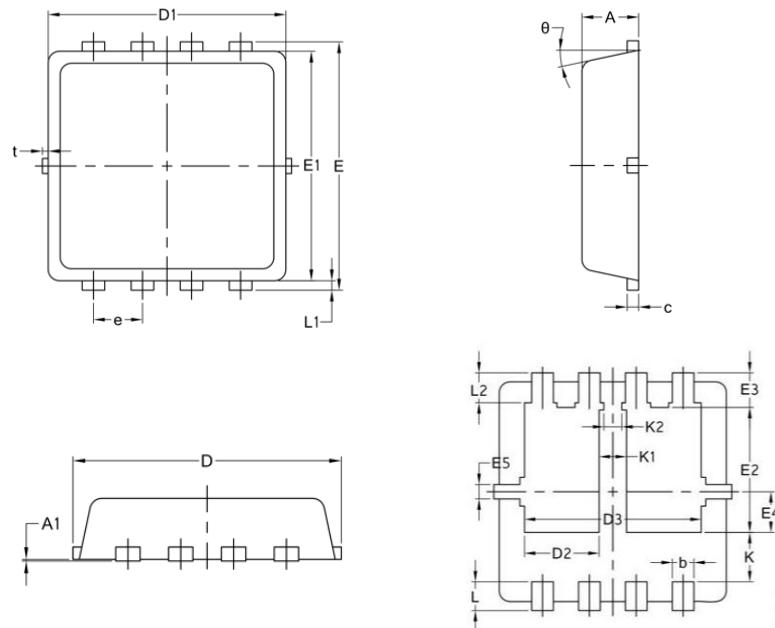
**Figure 9: Maximum Safe Operating Area**



**Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature**



**Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient**

**Package Mechanical Data-PDFN3\*3-8L Double**


Symbol	Common		
	Mm		
	Min	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.25	0.30	0.39
c	0.14	0.152	0.20
D	3.20	3.30	3.45
D1	3.05	3.15	3.25
D2	0.84	1.04	1.24
D3	2.30	2.45	2.60
E	3.20	3.30	3.40
E1	2.95	3.05	3.15
E2	1.60	1.74	1.90
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.50	0.69	0.80
K1	0.30	0.38	0.53
K2	0.15	0.25	0.35
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
L2	0.27	0.42	0.57
t	0	0.075	0.13
Φ	10°	12°	14°